

#### AMP

TE Internal #: 827914-3

Board-to-Board Jumpers & Shunts, AMPMODU MOD IV, Open Top, Board-to-Board, 2 Position, 2.54mm [.1in] Centerline, Printed

Circuit Board

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Shunt Type: AMPMODU MOD IV

Shunt Style: Open Top

Connector System: Board-to-Board

Number of Positions: 2

Centerline (Pitch): 2.54 mm [.1 in]

## **Features**

#### **Product Type Features**

Product Type Features	
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	2
Body Features	
Handle	Without
Contact Features	
Contact Mating Area Plating Material Thickness	3 μm[118.1 μin]
Contact Mating Area Plating Material	Tin
Contact Base Material	Beryllium Copper
Shunt Type	AMPMODU MOD IV
	Open Ton
Shunt Style	Open Top
Contact Current Rating (Max)	3 A
Contact Current Rating (Max)	

2.54 mm[.1 in]

Centerline (Pitch)



### **Dimensions**

Product Height	6 mm[.236 in]
Usage Conditions	
Operating Temperature Range	-40 - 85 °C, -40 - 85 °C[-40 - 185 °F][-40 - 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
CSA Certified	Yes
UL Rating	Recognized
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	1400
Packaging Method	Box
Other	

Loose piece of 142270-3

# **Product Compliance**

Comment

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2020 (205) Candidate List Declared Against: JAN 2020 (205) Does not contain REACH SVHC
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2020 (205) Candidate List Declared Against: JAN 2020 (205)
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer



This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

# **Customers Also Bought**











#### **Documents**

Product Specifications
Product Specification

English

**Product Environmental Compliance** 

TE Material Declaration

English